

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	361	(wafe substrate workpiece) with ("UBM" under adj bump)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/25 08:57
S8	361	(wafe substrate workpiece) with ("UBM" under adj bump)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:00
S10	20	S8 and ("LED" light adj emitt\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:22
S11	141	S8 and electrode	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:03
S12	83	S11 and reflow\$4	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:09
S13	60	S12 and metallurgy	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:09
S14	60	S13 and (metallurgy elctrode wafer substrate workpiece ubm under bump light emitt\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:11
S15	40	S14 and (printing print)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:11
S16	5	S15 and ("LED" light adj emitt\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/22 14:22